



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN APG-BOD/07/2868
Notification Date 09/10/2007

Die Thickness Reduction on VNQ830PEP-E.

BOD - CAR BODY

Table 1. Change Identification

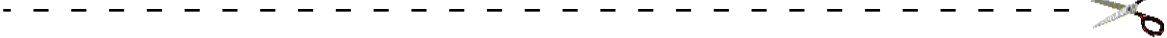
Product Identification (Product Family/Commercial Product)	VNQ830PEP-E / VNQ830PEPTR-E
Type of change	Waferfab process change
Reason for change	Improve Quality.
Description of the change	Die thickness reduction will be implemented on the product VNQ830PEP-E according to the requirements and commitment of the corrective action Report# F072020623FQS.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Data-Code
Manufacturing Location(s)	

Table 2. Change Implementation Schedule

Forecasted implementation date for change	03-Sep-2007
Forecasted availability date of samples for customer	03-Sep-2007
Forecasted date for STMicroelectronics change Qualification Plan results availability	03-Sep-2007
Estimated date of changed product first shipment	10-Dec-2007

Table 3. List of Attachments

Customer Part numbers list	
Qualification Plan results	



Customer Acknowledgement of Receipt	PCN APG-BOD/07/2868					
Please sign and return to STMicroelectronics Sales Office	Notification Date 09/10/2007					
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	<table border="1" style="width: 100%;"> <tr><td style="padding: 2px;">Name:</td></tr> <tr><td style="padding: 2px;">Title:</td></tr> <tr><td style="padding: 2px;">Company:</td></tr> <tr><td style="padding: 2px;">Date:</td></tr> <tr><td style="padding: 2px;">Signature:</td></tr> </table>	Name:	Title:	Company:	Date:	Signature:
Name:						
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DOCUMENT APPROVAL

Name	Function
Russo, Alfio	Division Marketing Manager
Aparo, Sebastiano	Division Product Manager
Parrino, Emanuele	Division Q.A. Manager



PRODUCT/PROCESS CHANGE NOTIFICATION®

**APG - CAR BODY DIVISION –
VIpower Business Unit – Catania**

Subject: Die Thickness Reduction on VNQ830PEP-E .

INVOLVED P&L FAMILY: 30

WHAT: In order to improve the quality of VNQ830PEP-E (silicon line VND3): will be implemented the die thickness reduction from 280um to 220 um according to the requirements and commitment of the corrective action Report # F072020623FQS.

WHY: In order to improve Quality .

WHO: Customer **SANMINA / VALEO.**

WHEN: The change will be implemented in according to the following scheduling:

- Samples will be available now.
- Qualification report already sent to Ctm.
- Start production: on wk49/2007.
- 1st shipment: wk49/2007, but, we are available to supply new production parts prior to stated ship date, upon Customer approval.

WHERE: CT6F Front End Diffusion Plant.

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